Product / Package Information

Package	LFCSP - Punched, Stacked Die
Body Size (mm)	12 X 12 X 0.80 (6.7 EP)
Lead Count	88
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.53E-01	86.91	869100	33.09	330912
Thermosets	Epoxy & Phenol Resin	Proprietary	2.25E-02	12.78	127800	4.87	48660
Other inorganic materials	Carbon black	1333-86-4	5.45E-04	0.31	3100	0.12	1180
Subtotal			1.76E-01	100.00	1000000	38.08	380753

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.50 E-01	96.20	962000	54.21	542086
Copper & its alloys	Nickel	7440-02-0	7.80 E-03	3.00	30000	1.69	16905
Copper & its alloys	Silicon	7440-21-3	1.69 E-03	0.65	6500	0.37	3663
Copper & its alloys	Magnesium	7439-95-4	3.90 E-04	0.15	1500	0.08	845
Subtotal			2.60 E-01	100.00	1000000	56.35	563499

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.60 E-03	100.0	1000000	0.56	5635

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.90 E-03	100.0	1000000	1.06	10617

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.01 E-03	100.0	1000000	0.65	6523

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.26 E-02	100.0	1000000	2.73	27264

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.33 E-03	73.54	735400	0.29	2891
Other organic materials	Epoxy resin A	TS ref# 10013	1.33 E-04	7.35	73500	0.03	289
Others	Anhydride	TS ref# 10181	1.33 E-04	7.35	73500	0.03	289
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	5.34 E-05	2.94	29400	0.01	116
Other organic materials	Epoxy resin B	TS ref# 10237	5.34 E-05	2.94	29400	0.01	116
Others	Epoxy resin modifier	TS ref# 10038	5.34 E-05	2.94	29400	0.01	116
Others	Anhydride	TS ref# 10180	5.34 E-05	2.94	29400	0.01	116
Subtotal			1.82 E-03	100.0	1000000	0.39	3932

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Resin	Proprietary	4.10 E-04	50.0	500000	0.09	888
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	3.69 E-04	45.0	450000	0.08	799
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	4.10 E-05	5.0	50000	0.01	89
Subtotal			8.20 E-04	100.0	1000000	0.18	1776

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.62 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.